#### Nch 190V 10A Power MOSFET

$V_{DSS}$	190V
R <sub>DS(on)</sub> (Max.)	182mΩ
I <sub>D</sub>	±10A
P <sub>D</sub>	85W

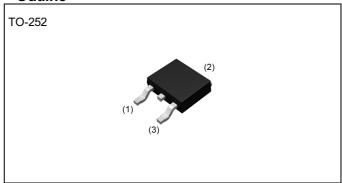
#### Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free plating; RoHS compliant

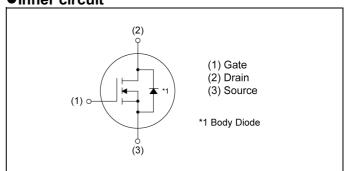
### Application

**Switching Power Supply** 

#### Outline



### •Inner circuit



Packaging specifications

Packing	Embossed Tape
Packing code	TL1
Marking	RD3S100CN
Basic ordering unit (pcs)	2500

### ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	190	V
Continuous drain current (T <sub>c</sub> = 25°C)	I <sub>D</sub> *1	±10	А
Pulsed drain current	I <sub>DP</sub> *2	±40	А
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	l <sub>AS</sub> *3	5.0	А
Avalanche energy, single pulse	E <sub>AS</sub> *3	8.33	mJ
Power dissipation (T <sub>c</sub> = 25°C)	P <sub>D</sub>	85	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

#### ●Thermal resistance

Downwortow	Cymah al	Values			1.1
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>	-	-	1.46	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	147	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# • Electrical characteristics $(T_a = 25^{\circ}C)$

Davamatar	Cymah al	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V$ , $I_D = 1mA$	190	-	1	V
		V <sub>DS</sub> = 190V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	T <sub>j</sub> = 25°C	-	-	10	μΑ
		T <sub>j</sub> = 125°C	-	-	100	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	0.5	-	2.5	V
		V <sub>GS</sub> = 10V, I <sub>D</sub> = 5A				
		$T_j = 25^{\circ}C$	-	130	182	
Static drain - source on - state resistance	R <sub>DS(on)</sub> *4	$T_j = 125^{\circ}C$	-	195	ı	mΩ
		$V_{GS} = 4V$ , $I_D = 5A$		136	190	
		$T_j = 25^{\circ}C$	_	130	190	
Gate resistance	$R_G$	f = 1MHz, open drain	-	4.5	-	Ω

### ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davanastan	C: male al	Conditions	Values			Unit
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Unit
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = 10V, I <sub>D</sub> = 5.0A	6	12	-	S
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	2000	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	95	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	60	-	
Turn - on delay time	t <sub>d(on)</sub> *4	V <sub>DD</sub> ≈ 100V, V <sub>GS</sub> = 10V	-	15	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 5A	-	20	-	
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 20\Omega$	-	140	-	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	75	-	

### ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Davamatar	Cumphal	Conditions	Values			l limit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Qg*4	V <sub>DD</sub> ≈ 100V	-	52	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 10A	-	5	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	V <sub>GS</sub> = 10V	-	11	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 100V, I <sub>D</sub> = 10A	-	2.5	-	V

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L  $\simeq$  500 $\mu$ H, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , starting T<sub>j</sub> = 25°C

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Source current	I <sub>S</sub> *1	· T <sub>C</sub> = 25°C	1	-	10	Α
Pulsed source current	I <sub>SP</sub> *2	1C - 23 C	1	-	40	Α
Source-Drain voltage	V <sub>SD</sub> *4	$V_{GS} = 0V, I_{S} = 10A$	-	-	1.5	V
Reverse recovery time	t <sub>rr</sub> *4		1	95	1	ns
Reverse recovery charge	Q <sub>rr</sub> *4	I <sub>S</sub> = 5A di/dt = 100A/μs	-	255	-	nC
Peak reverse recovery current	I <sub>rr</sub>		-	5.5	-	Α

Fig.1 Power Dissipation Derating Curve

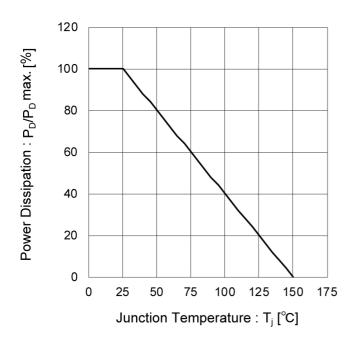


Fig.2 Maximum Safe Operating Area

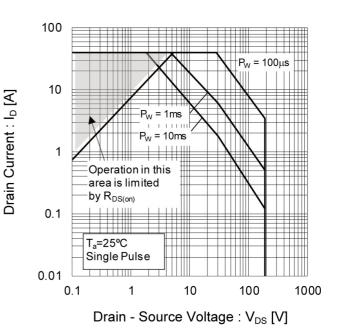


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

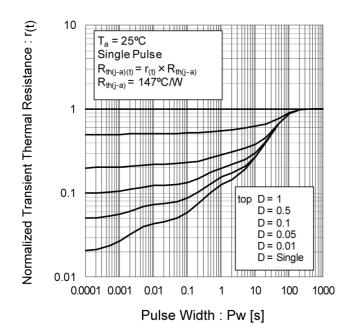


Fig.4 Avalanche Current vs. Inductive Load

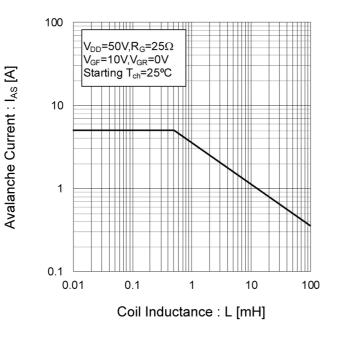


Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature

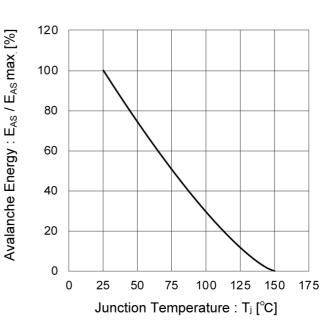
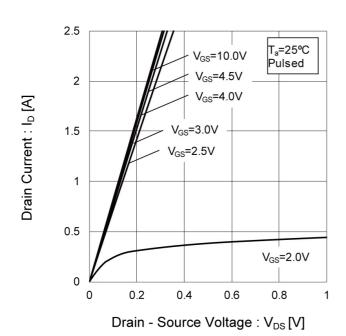


Fig.6 Typical Output Characteristics(I)



Drain Current : I<sub>D</sub> [A]

10 V<sub>GS</sub>=10.0V T<sub>a</sub>=25℃ 9 Pulsed V<sub>GS</sub>=4.5V 8 V<sub>GS</sub>=4.0V 7 V<sub>GS</sub>=3.0V 6 V<sub>GS</sub>=2.8V 5 4 3 2 V<sub>GS</sub>=2.0V 1 0 0 2 6 10

Fig.7 Typical Output Characteristics(II)

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.8 Breakdown Voltage vs. Junction Temperature

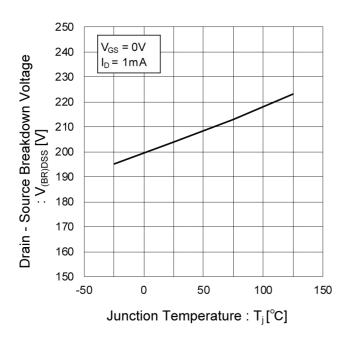


Fig.9 Typical Transfer Characteristics

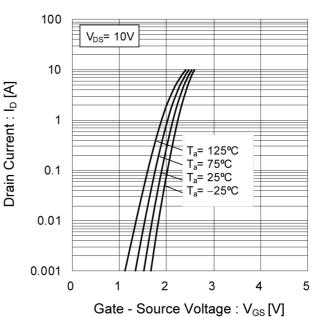


Fig.10 Gate Threshold Voltage vs. Junction Temperature

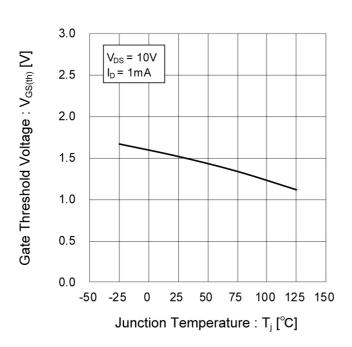


Fig.11 Transconductance vs. Drain Current

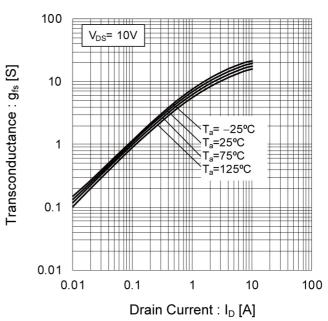


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

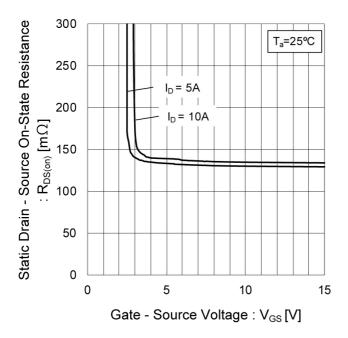


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current( I )

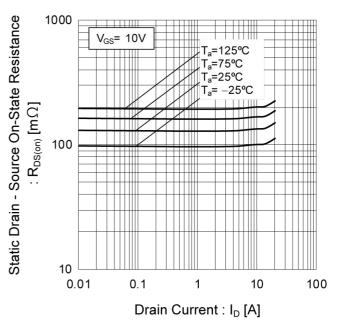


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current( II )

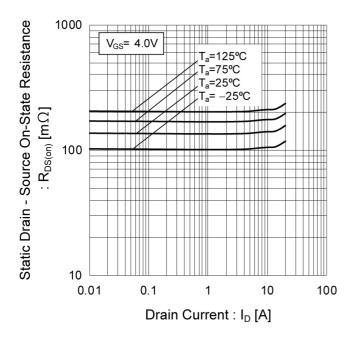


Fig.15 Static Drain - Source On - State Resistance vs. Junction Temperature

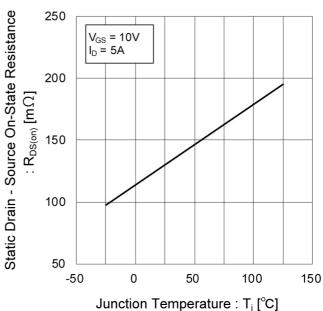


Fig.16 Source Current vs. Source-Drain Voltage

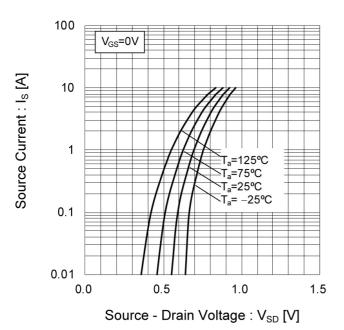


Fig.17 Source Current vs. Reverse Recovery Time

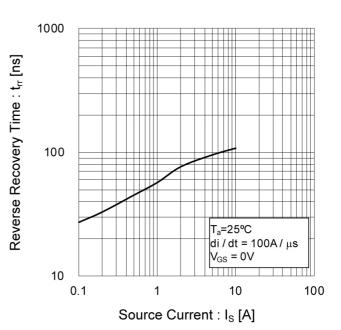


Fig.18 Typical Capacitance vs. Drain - Source Voltage

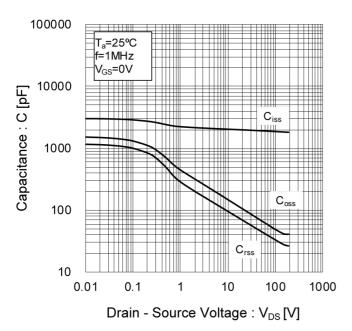


Fig.19 Switching Characteristics

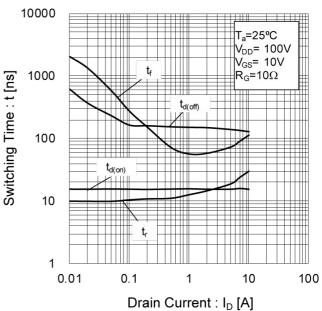
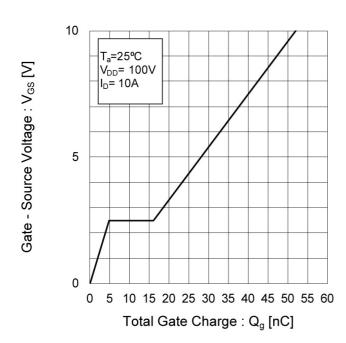


Fig.20 Dynamic Input Characteristics



#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

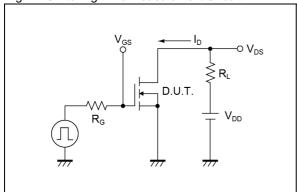


Fig.2-1 Gate Charge Measurement Circuit

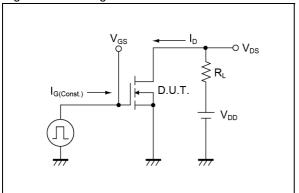


Fig.3-1 Avalanche Measurement Circuit

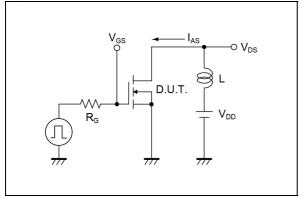


Fig.4-1 trr Measurement Circuit

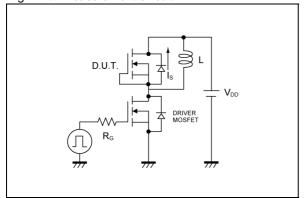


Fig.1-2 Switching Waveforms

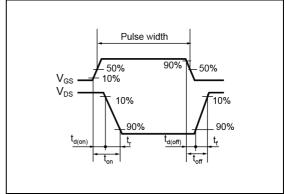


Fig.2-2 Gate Charge Waveform

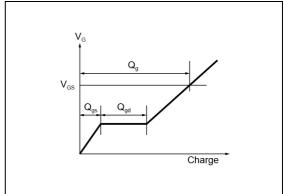


Fig.3-2 Avalanche Waveform

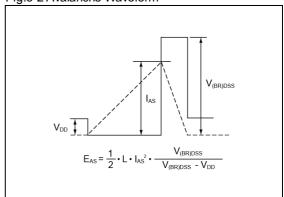
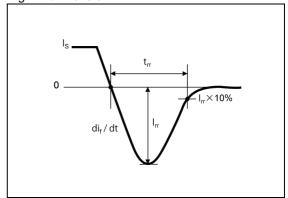
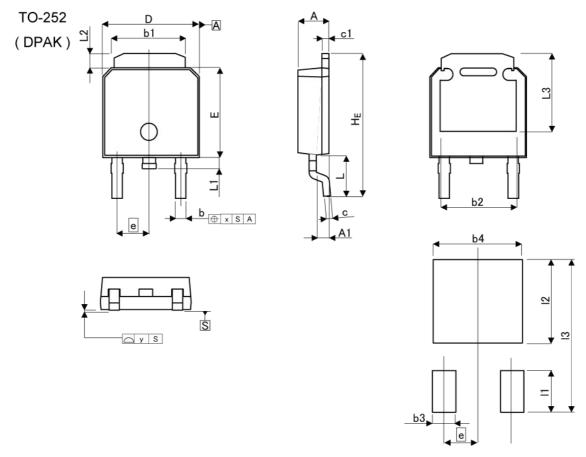


Fig.4-2 trr Waveform



#### Dimensions



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	MILIMETERS		HES
DIIVI	MIN	MAX	MIN	MAX
Α	2.20	2.40	0.087	0.094
A1	0.70	1.10	0.028	0.043
b	0.60	0.90	0.024	0.035
b1	5.20	5.50	0.205	0.217
b2	5.	35	0.2	211
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.091	
E	6.00	6.40	0.236	0.252
HE	9.40	10.40	0.370	0.409
L	2.	70	0.1	06
L1	0.60	1.00	0.024	0.039
L2	0.70	1.30	0.028	0.051
L3	5.30		0.2	209
Х	-	0.25	-	0.010
у	-	0.10	-	0.004

DIM	MILIMETERS		MILIMETERS		INC	HES
DIIVI	MIN	MAX	MIN	MAX		
b3	127	1.15	51	0.045		
b4	- (	5.55		0.219		
I1	-	2.77	1	0.109		
12	1=0	5.50	-	0.217		
13	-	10.40	-	0.409		

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
CLASSⅢ	ОГАССШ	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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# RD3S100CN - Web Page

Part Number	RD3S100CN
Package	TO-252
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes